

FAST - [Untitled1.1]

Drafts

Pending

Active

L11: (12528) substrate near resin

L12: (1667) 11 and (hole or (through adj hole))

L13: (3) 12 and (chip or component or capacitor or resistor or inductor) near embedded

L14: (10) 4965653.URPN.

L15: (175) 12 and embedded

L16: (201) (174/265).CCLS.

L18: (1) 3536565.URPN.

L28: (218) 12 and ((row and column) or matrix)

L29: (155) 28 and (IC or chip or component or wafer)

L30: (413) (324/763).CCLS.

L31: (4) ("3290756").PN.

L33: (30) 3290756.URPN.

L34: (2) ("4979076").PN.

L35: (13) ("3142783" | "3191098" | "3192307" | "3266125" | "3290756" | "3480836" | "3517272".

L43: (17) 3142783.URPN.

L44: (368) (361/764).CCLS.

L45: (17) ("4299873" | "4417297" | "4800459" | "5045381" | "5153987" | "5324687" | "5401688".

L46: (201) (174/265).CCLS.

Report

Log

Reverse

Queue

Reset

DES

USPAT EPO JPO DEAWENT USOPR

☒ Highlight Internals Only

174/265

	U	Document ID	Issue Dat	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C	P		
1	<input type="checkbox"/>	US 6500011	20021231	6	Flexure blank and method of manufacturing the same	439/82	174/262; 174/264	174/265	Fujita, Norimasa et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	<input type="checkbox"/>	US 6489572	20021203	4	Substrate structure for an integrated circuit package a	174/259	156/245; 158/298	174/265	Ho, Mon Nan et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
3	<input type="checkbox"/>	US 6486415	20021126	8	Compliant layer for encapsulated columns	174/263	174/261; 174/265	174/265	Jimarez, Lisa J. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
4	<input type="checkbox"/>	US 6486414	20021126	15	Through-hole structure and printed circuit board includi	174/261	174/255; 174/262	174/265	Kobayashi, Kaoru et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
5	<input type="checkbox"/>	US 6462285	20021008	14	Wave solder application for ball grid array modules with	174/265	174/260; 174/263	174/265	Enroth, Wesley M. et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	<input type="checkbox"/>	US 6459047	20021001	8	Laminate circuit structure and method of fabrication	174/256	174/255; 174/259	174/265	Japp, Robert M. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
7	<input type="checkbox"/>	US 6444925	20020903	19	Press-fit pin connection checking method and syste	174/262	174/255; 174/261	174/265	Teshima, Yasuhiro et al	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	<input type="checkbox"/>	US 6444918	20020903	25	Interconnection structure of semiconductor element	174/250	174/262; 174/265	174/265	Umemura, Eiichi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	<input type="checkbox"/>	US 6441479	20020827	15	System-on-a-chip with multi-layered metallized thro	257/700	174/262; 174/265	174/265	Ahn, Kie Y. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

Ready

NUM